



May 12, 2008

To: Mr. John D'Ambrosia, IEEE 802.3BA Chair; jdambrosia@ieee.org
Cc: Mr. David Stauffer; IBM Microelectronics; dstauffe@us.ibm.com
Mr. Bob Grow, IEEE Chair 802.3; bob.grow@ieee.org
Mr. Wael William Diab; Secretary, IEEE 802.3 Ethernet Working Group;
wdiab@broadcom.com

From: Mr. Lyndon Ong, OIF TC Chair; Lyong@Ciena.com

Subject: **OIF Common Electrical I/O – 28 Gbps – Short Reach Project**

Dear John,

As part of the OIF CEI-25 project, the OIF PLL WG has been working on the definition of an electrical interface for chip-to-chip and chip-to-optics module applications operating at baud rates up to 28 Gbps. This CEI-28G-SR interface is intended to be included as an additional clause in a future revision of the "OIF-CEI-02.0 Common Electrical I/O (CEI)" Implementation Agreement. The attached document is a draft of this clause and represents work in progress.

We welcome IEEE 802.3BA comments on this document.

Best regards,

A handwritten signature in black ink, appearing to read "Lyndon Ong", is positioned below the "Best regards," text.

Lyndon Ong
OIF Technical Committee Chair

Attachment: oif2008.029.02